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Product Change Notification - GBNG-29PLBE459

Date: 06 Oct 2016
Product Category: SMSC
Notification subject: CCB 2756 Initial Notice: Qualification of ASE assembly site for selected products available in 48L LQFP (7x7mm) package.
Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE assembly site for selected products available in 48L LQFP (7x7mm) package.

Pre Change:

Assembled at TICP assembly site using silver (Ag) or gold (Au) wire, EN4900 die attach and CEL-9200 mold compound.

Post Change:

Assembled at ASE assembly site using gold (Au) wire, CRM1076WA die attach and G631H mold compound.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	TICP	ASE
Wire material	Ag wire or Au wire	Au wire
Die attach material	EN4900	CRM1076WA
Molding compound material	CEL-9200	G631H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying ASE assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

February 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

Workweek	October 2016					->	February 2017			
	40	41	42	43	44		5	6	7	8
Initial PCN Issue Date		X								
Qual Report Availability							X			
Final PCN Issue Date							X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

October 4, 2016: Issued initial notification.

October 6, 2016: Re-issued the initial notification to notify all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-29PLBE459_Qual Plan.pdf](#)

[PCN_GBNG-29PLBE459_Affected CPN.pdf](#)

[PCN_GBNG-29PLBE459_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_GBNG-29PLBE459
CATALOG_PART_NBR
KSZ8081MLXCA
KSZ8081MLXCA-TR
KSZ8081MLXIA
KSZ8081MLXIA-TR
KSZ8091MLXCA
KSZ8091MLXCA-TR
KSZ8091MLXIA
SPNY801146
SPNY801146-TR
SPNY801151
SPNY801151-TR
SPNZ801146
SPNZ801146-TR
SPNZ801151
SPNZ801151-TR